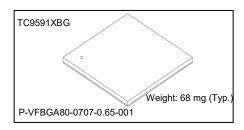
CMOS Digital Integrated Circuit Silicon Monolithic

# **TC9591XBG**

#### **Automotive Peripheral Devices**

#### Overview

The MIPI® CSI-2<sup>SM</sup> to Parallel port and Parallel port to CSI-2 (TC9591XBG) is a bridge device that has both functions to convert MIPI data transfers from devices such as a camera to an application processor over a Parallel port interface and to convert parallel data transfers to an application over a MIPI CSI-2 interface. All internal registers can be accessed through I<sup>2</sup>C or SPI (in CSI out case only).



#### **Features**

- CSI-2 TX/RX interface
- → MIPI CSI-2 compliant (Version 1.01 Revision 0.04 2 April 2009)
- ♦ Configurable to TX or RX controller
- ♦ Supports up to 1Gbps per data lane
- ♦ Supports up to 4 data lanes
- Supports video data formats
- RX: RAW8/10/12/14, YUV422 (CCIR/ITU 8/10-bit), RGB888/666/565 and User-Defined 8-bit
- TX: YUV422 (CCIR/ITU 8/10-bit), YUV444, RGB888/666/565 and RAW8/10/12/14
- Parallel Port Interface
- ♦ Supports data formats
- 24-bit bus un-packed format (Both Input and Output mode)
  - RGB888/666/565, RAW8/10/12/14 and YUV422 8-bit (on 8/16-bit data bus) and 10-bit data formats.
- > YUV444 (Parallel Input mode only)
- YUV422 8-bit ITU BT.656 and ITU BT.601 (Parallel input mode only)
  - ➤ Up to 100 MHz PCLK frequency for Output mode, and 166 MHz for Input mode.
- I<sup>2</sup>C Slave Interface (CS = L)
- ♦ Configure all TC9591XBG internal registers
- SPI Slave Interface (Only applicable in CSIOut configuration, MSEL = H, and CS = H)
  - SPI interface support for up to 25 MHz operation.
  - ♦ Configure all TC9591XBG internal registers

- GPIO signals
- ♦ 3 GPIO signals
  - Three GPIO signals can be configured as control signals (MCLK, CXRST, XShutdown) for CSI-2 RX device.
- Or one GPIO signal can be configured as INT signal for Parallel interface.
- System
- Clock and power management support to achieve low power states.
- Power supply inputs
- ♦ Core and MIPI D-PHY: 1.2 V
- ♦ I/O: 1.8 V or 3.3 V
- Operation temperature Ta = -40 °C to 105 °C
- AEC-Q100 qualified with the following definition
- → Grade 2 : -40 °C to 105 °C ambient operating temperature range



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#### **REFERENCES**

- MIPI D-PHY, "MIPI\_D-PHY\_specification\_v01-00-00, May 14, 2009"
   MIPI CSI-2, "MIPI Alliance Standard for Camera Serial Interface 2 (CSI-2) Version 1.01 Revision Nov 2010"
- 3. I<sup>2</sup>C bus specification, version 2.1, January 2000, Philips Semiconductor

### 1. Overview

The MIPI CSI-2 to Parallel port and Parallel port to CSI-2 (TC9591XBG) is a bridge device that has both functions to convert MIPI data transfers from devices such as a camera to an application processor over a Parallel port interface and to convert parallel data transfers to an application over a MIPI CSI-2 interface. All internal registers can be accessed through I<sup>2</sup>C or SPI (in CSI out case only).

There are several system configurations where TC9591XBG is typically used.

- CSI-2 RX with Parallel output mode for scanner application. In this mode, TC9591XBG (CSI-2 to Parallel converter) is a bridge device that converts serial data transfers from devices such as a camera to an application processor over a parallel interface.
- CSI-2 TX with Parallel Input mode for Analog TV, TelePresence Type, and Specialty/Older Cameras application. In this mode, TC9591XBG (Parallel to CSI-2 converter) is a bridge device that converts parallel data transfers to an application over a MIPI CSI-2 interface.

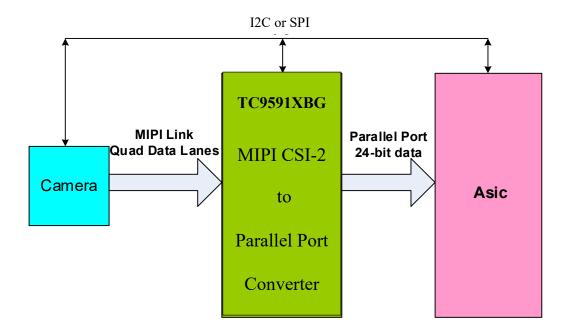


Figure 1.1 System Overview with TC9591XBG in CSI-2 RX to Parallel Port Configuration



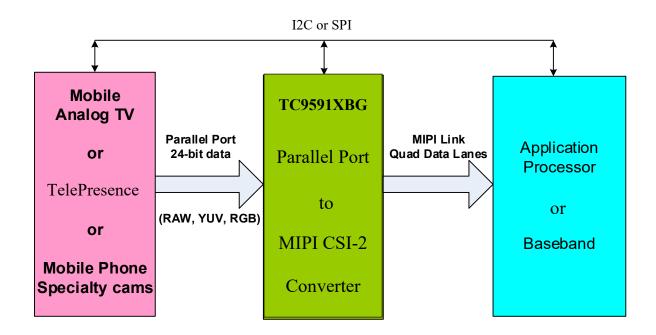


Figure 1.2 System Overview with TC9591XBG in Parallel Port to CSI-2 TX Configuration



### 2. Features

Below are the main features supported by TC9591XBG.

- CSI-2 TX/RX Interface
  - ♦ MIPI CSI-2 compliant (Version 1.01 Revision 0.04 2 April 2009)
  - → Configurable to TX or RX controller
  - ♦ Supports up to 1Gbps per data lane
  - ♦ Supports up to 4 data lanes
  - Supports video data formats
    - RX: RAW8/10/12/14, YUV422 (CCIR/ITU 8/10-bit), RGB888/666/565 and User-Defined 8-bit
    - TX: YUV422 (CCIR/ITU 8/10-bit), YUV444, RGB888/666/565 and RAW8/10/12/14
- Parallel Port Interface
  - Supports data formats
    - 24-bit bus un-packed format (Both Input and Output mode)
      - RGB888/666/565, RAW8/10/12/14 and YUV422 8-bit (on 8/16-bit data bus) and 10-bit data formats.
    - > YUV444 (Parallel Input mode only)
    - YUV422 8-bit ITU BT.656 and ITU BT.601 (Parallel input mode only)
  - ♦ Up to 100 MHz PCLK frequency for Output mode, and 166 MHz for Input mode.
- I<sup>2</sup>C Slave Interface (CS = L)
  - ♦ Support for normal (100 kHz), fast mode (400 kHz) and special mode (1 MHz)
  - ♦ Configure all TC9591XBG internal registers
- SPI Slave Interface (Only applicable in CSIOut configuration, MSEL = H, and CS = H)
  - ♦ SPI interface support for up to 25 MHz operation.
  - ♦ Configure all TC9591XBG internal registers
- GPIO signals
  - ♦ 3 GPIO signals
    - Three GPIO signals can be configured as control signals (MCLK, CXRST, XShutdown) for CSI-2 RX device.
    - Or one GPIO signal can be configured as INT signal for Parallel interface.
- System
  - Clock and power management support to achieve low power states.
- Power supply inputs
  - ♦ Core and MIPI D-PHY: 1.2 V
  - ♦ I/O: 1.8 V or 3.3 V
- AEC-Q100 Qualified with the following definition
  - ♦ Grade 2: -40 °C to 105 °C ambient operating temperature range



## 2.1. Typical Power Consumption

Parallel_In → CSI_Out, 500 MHz CSICLk, 1080P @60fps						
	VDDIO (3.3 V) VDDC (1.2 V) VDD_MIPI (1.2 V) Total Power					
Current (mA)	0.44	40.4	24.5			
Power (mW)	1.45	48.48	29.40	79.33		

CSI_In → Parallel_Out, 500 MHz CSICLk, 100 MHz PClk ColorBar @60fps					
VDDIO (3.3 V) VDDC (1.2 V) VDD_MIPI (1.2 V) Total Power					
Current (mA)	18.9	13.9	12.3		
Power (mW)	62.37	16.68	14.76	93.81	



### 3. External Pins

## 3.1. TC9591XBG pinout description

TC9591XBG resides in BGA pin packages. The following table gives the signals of TC9591XBG and their function.

Table 3.1 TC9591XBG Functional Signal List

			0		Initial	netional digital List	
Group	Pin Name	MSEL=0	MSEL=1	Type	(O)	Function	Note
	RESX	I	I	Sch	-	System reset input, active low	-
	REFCLK	I	I	N	-	Reference clock input (6MHz – 40MHz)	-
	MSEL	I	I	N	-	Mode Select 1'b0: CSI-2 RX in -> Parallel out 1'b1: Parallel in -> CSI-2 TX	-
System: Reset & Clock (4)	CS	I	I	N	-	Chip Select, active low  MSEL= 0 (CSI-2 RX in -> Parallel out)  - When CS = 0, chip selected  Normal operation  - When CS = 1, chip not selected  Cannot access to internal registers and optionally Parallel output ports can be tri-state when 0x0004[15] is set  MSEL= 1 (Parallel in -> CSI-2 TX)  - CS = 0, I <sup>2</sup> C I/F is selected  - CS = 1, SPI I/F is chosen	-
	MIPI_CP	I	0	PHY	LP11	MIPI-CSI clock positive	-
	MIPI_CN	I	0	PHY	LP11	MIPI-CSI clock negative	-
	MIPI_D0P	I	0	PHY	LP11	MIPI-CSI Data 0 positive	-
	MIPI D0N	I	0	PHY	LP11	MIPI-CSI Data 0 negative	-
MIPI-CSI	MIPI D1P	I	0	PHY	LP11	MIPI-CSI Data 1 positive	-
(10)	MIPI D1N	1	0	PHY	LP11	MIPI-CSI Data 1 negative	_
	MIPI D2P	i	0	PHY	LP11	MIPI-CSI Data 2 positive	_
	MIPI D2N	i	Ö	PHY	LP11	MIPI-CSI Data 2 negative	-
	MIPI_D3P	I	0	PHY	LP11	MIPI-CSI Data 3 positive	-
	MIPI_D3N	I	0	PHY	LP11	MIPI-CSI Data 3 negative	-
12C I/F	I2C_SCL	l	I	Sch	-	I <sup>2</sup> C serial clock or SPI_SCLK	4 mA
(2)	I2C_SDA	ļ	ļ	Sch	-	I <sup>2</sup> C serial data or SPI_MOSI	4 mA
Parallel	PD[23:0]	0	I	N	L	Parallel Port Data - PD[23:12] can configs to be GPIO[15:4]	4 mA
Port I/F	VVALID	0	I	N	L	Parallel port VVALID signal	4 mA
(27)	HVALID	0	1	N	L	Parallel port HVALID signal	4 mA
	PCLK	0	1	N	L	Parallel Port Clock signal	4 mA
GPIO (3)	GPIO[2:0]	ı	ı	N	-	GPIO[2:0] signals  CSI-2 RX in -> Parallel out - (GPIO[0] option to become MCLK signal) - (GPIO[1] option to become CXRST or INT) - (GPIO[2] option to become XShutdown)  Parallel in -> CSI-2 TX - (GPIO[0] option to become MCLK signal) - (GPIO[1] option to become SPI_SS or INT) - (GPIO[2] option to become SPI_MISO)	4 mA
	VDDC (1.2 V)	NA	-	-	-	VDD for Internal Core (2)	-
POWER (9)	VDDIO (1.8 V or 3.3 V)	NA	-	-	-	VDDIO is for IO power supply (3)	-
(9)	VDD_MIPI (1.2 V)	NA	-	-	-	VDD for the MIPI CSI2 (2)	-
Ground (25)	VSS	NA	-	-	_	Ground	-



## 3.2. TC9591XBG BGA80 Pin Count Summary

Table 3.2 TC9591XBG BGA 80 Pin Count Summary

Group Name	Pin Count	Notes
SYSTEM	4	-
MIPI-CSI	10	-
I2C I/F	2	-
GPIO	3	-
Parallel Port I/F	27	-
POWER	9	IO, MIPI and Core Power
GROUND	25	-
TOTAL	80	



## 3.3. TC9591XBG Pin Layout

A1	A2	А3	<b>A4</b>	<b>A5</b>	<b>A6</b>	<b>A7</b>	<b>A8</b>	<b>A9</b>	A10
VSS	PD17	PD19	PD21	PD23	GPIO2	VDDC	I2C_SCL	MSEL	VSS
B1	B2	В3	В4	<b>B</b> 5	В6	В7	<b>B</b> 8	В9	B10
VDDC	PD16	PD18	PD20	PD22	GPIO1	VSS	I2C_SDA	RESX	VDDIO
C1	C2	<b>C</b> 3	C4	<b>C</b> 5	C6	<b>C7</b>	C8	C9	C10
PD15	PD14							MIPI_D3P	MIPI_D3N
D1	D2	D3	D4	<b>D</b> 5	D6	D7	D8	D9	D10
PD13	PD12		VSS	VSS	VSS	VSS		MIPI_D2P	MIPI_D2N
E1	E2	<b>E</b> 3	E4	<b>E</b> 5	E6	E7	E8	E9	E10
PD11	PD10		VSS	VSS	VSS	VSS		VSS	VDD_MIPI
F1	F2	F3	F4	F5	F6	F7	F8	F9	F10
PD9	PD8		VSS	VSS	VSS	VSS		MIPI_CP	MIPI_CN
<b>G</b> 1	G2	G3	G4	G5	G6	<b>G</b> 7	G8	G9	G10
PD7	PD6		VSS	VSS	VSS	VSS		MIPI_D1P	MIPI_D1N
H1	H2	Н3	Н4	H5	Н6	Н7	Н8	Н9	H10
VDDIO	VSS							VSS	VDD_MIPI
J1	J2	J3	J4	J5	J6	J7	J8	J9	J10
PD4	PD2	PD0	VSS	VSS	PCLK	HVALID	CS	MIPI_D0P	MIPI_D0N
							1.70		
<b>K</b> 1	K2	K3	K4	<b>K</b> 5	K6	<b>K</b> 7	K8	K9	K10

Figure 3.1 TC9591XBG 80-Pin Layout (Top View)

## 4. Package

### 4.1. TC9591XBG Package

The packages for TC9591XBG are described in the figures below.

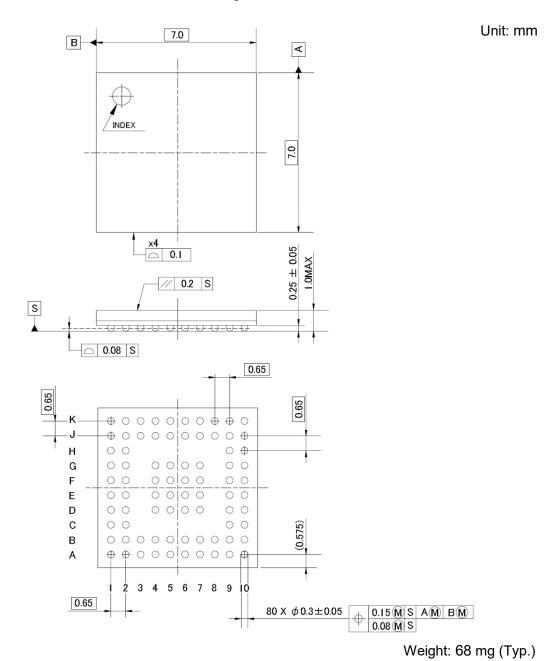


Figure 4.1 TC9591XBG P-VFBGA80-0707-0.65-001 package

Table 4.1 TC9591XBG P-VFBGA80-0707-0.65-001 Mechanical Dimension

Dimension	Min	Тур.	Max
Solder ball pitch	-	0.65 mm	-
Solder ball height	0.20 mm	0.25 mm	0.30 mm
Package dimension	-	7.0 × 7.0 mm <sup>2</sup>	-
Package height	-	-	1.0 mm

### 5. Electrical Characteristics

## **5.1. Absolute Maximum Ratings**

VSS= 0V reference

Parameter	Symbol	Rating	Unit
Supply voltage (1.8V - Digital IO)	VDDIO	-0.3 to +3.9	V
Supply voltage (1.2V – Digital Core)	VDDC	-0.3 to +1.8	V
Supply voltage (1.2V – MIPI CSI PHY)	VDD_MIPI	-0.3 to +1.8	V
Input voltage (CSI IO)	V <sub>IN_CSI</sub>	-0.3 to VDD_MIPI+0.3	V
Output voltage (CSI IO)	V <sub>OUT_CSI</sub>	-0.3 to VDD_MIPI+0.3	V
Input voltage (Digital IO)	V <sub>IN_IO</sub>	-0.3 to VDDIO+0.3	V
Output voltage (Digital IO)	V <sub>OUT_IO</sub>	-0.3 to VDDIO+0.3	V
Junction temperature	Tj	125	°C
Storage temperature	Tstg	-40 to +125	°C

### **5.2. Operating Condition**

VSS= 0V reference

Parameter	Symbol	Min	Тур.	Max	Unit
Supply voltage (1.8V – Digital IO)	VDDIO	1.65	1.8	1.95	V
Supply voltage (3.3V – Digital IO)	VDDIO	3.0	3.3	3.6	V
Supply voltage (1.2V – Digital Core)	VDDC	1.1	1.2	1.3	V
Supply voltage (1.2V – MIPI CSI PHY)	VDD_MIPI	1.1	1.2	1.3	V
Operating temperature (ambient temperature with voltage applied)	Та	-40	+25	+105	°C
Supply Noise Voltage	$V_{SN}$	-	-	100	$mV_{pp}$



### 5.3. DC Electrical Specification

Parameter	Symbol	Min	Тур.	Max	Unit
Input voltage, High level input Note1	V <sub>IH</sub>	0.7 VDDIO	-	VDDIO	٧
Input voltage, Low level input Note1	$V_{IL}$	0	-	0.3 VDDIO	V
Input voltage High level CMOS Schmitt Trigger Note1, Note2	V <sub>IHS</sub>	0.7 VDDIO	-	VDDIO	V
Input voltage Low level CMOS Schmitt Trigger Note1, Note2	V <sub>ILS</sub>	0	-	0.3 VDDIO	V
Output voltage High level Note1, Note2 (Condition: IOH = -0.4mA)	V <sub>он</sub>	0.8 VDDIO	-	VDDIO	V
Output voltage Low level	V <sub>OL</sub>	0	-	0.2 VDDIO	V
(Condition: IOL = 2mA) Input leak current, High level (Normal IO or Pull-up IO) (Condition: VIN = +VDDIO, VDDIO = 3.6V)	I <sub>ILH1</sub> (Note4)	-10	-	10	μΑ
Input leak current, High level (Pull-down IO) (Condition: VIN = +VDDIO, VDDIO = 3.6V)	I <sub>ILH2</sub> (Note4)	-	-	100	μΑ
Input leak current, Low level (Normal IO or Pull-down IO) (Condition: VIN = 0V, VDDIO = 3.6V)	I <sub>ILL1</sub> (Note5)	-10	-	10	μA
Input leak current, Low level (Pull-up IO) (Condition: VIN = 0V, VDDIO = 3.6V)	I <sub>ILL2</sub> (Note5)	-	-	200	μA

Note1: Each power source is operating within operation condition.

Note2: Current output value is specified to each IO buffer individually. Output voltage changes with output

current value.

Note4: Normal pin or Pull-up IO pin applied VDDIO supply voltage to Vin (input voltage)

Note5: Normal pin or Pull-down IO pin applied VSSIO (0V) to Vin (input voltage)



# 6. Revision History

Table 6.1 Revision History

Revision	Date	Description
1.0	2020-06-05	Newly released



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